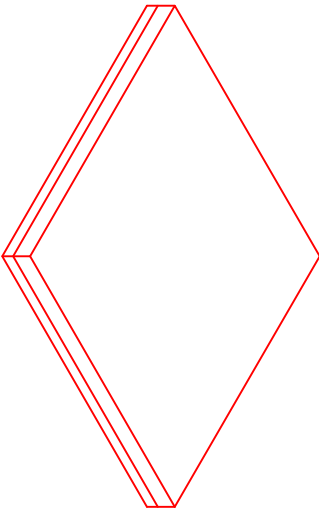


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REV.	DESCRIPTION	DATE	CHECKED	ORIGINATED BY
00	INITIAL RELEASE PER DCN C06106	06/06/99	E.B.	M.C.N.



7. REFERENCE SPECIFICATIONS:
A. AAP SPEC #001-2294: PLACING OPERATION PROCEDURE.
B. AAP SPEC #001-0619-2002: MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 49.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 7 X 7.
2. THE BASIC SOLDER BUMP GRID PITCH IS 0.80mm.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS		ANGULARS ±1°		PRODUCTION		APPROVALS		DATE		TITLE	
DECIMAL	XX ±0.10	XX ±0.05	XX ±0.03	DATE	04/14/99	DATE	04/29/99	DATE	04/14/99	DATE	04/14/99
ANGULAR	N/A	N/A	N/A	DATE	04/14/99	DATE	04/29/99	DATE	04/14/99	DATE	04/14/99
PROVIDE	N/A	N/A	N/A	DATE	04/14/99	DATE	04/29/99	DATE	04/14/99	DATE	04/14/99
DO NOT SCALE DRAWING	N/A	N/A	N/A	DATE	04/14/99	DATE	04/29/99	DATE	04/14/99	DATE	04/14/99

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cinqm

PACKAGE OUTLINE - CTBGA 49,
6.00mm X 6.00mm, 2 LAYER,
0.80mm PITCH, LAMINATE SUBSTRATE, AAP

DATE	04/14/99	DATE	04/29/99	DATE	04/14/99
BY	B	BY	N/A	BY	75445
APP'D	N/A	APP'D	N/A	APP'D	00
SCALE	8:1	SCALE	8:1	SCALE	8:1
SHEET	1 OF 3	SHEET	1 OF 3	SHEET	1 OF 3